

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

- 1           1. (Previously Presented) A pressure sensor comprising an integrated circuit  
2        encapsulated within a package, said integrated circuit including a pressure sensing element, an  
3        opening being provided in the package allowing the pressure sensor to be exposed to the  
4        atmosphere wherein a filter extends across the opening thereby preventing the ingress of  
5        moisture or other substances.
  
- 1           2. (Original) A pressure sensor as claimed in claim 1 wherein the integrated  
2        circuit incorporates a radio frequency transponder or other means for connecting or transmitting  
3        the output of the pressure sensing element to external circuitry.
  
- 1           3. (Previously Presented) A pressure sensor as claimed in claim 1 wherein  
2        the filter is fixed to the surface of the package such that it extends over and covers the opening.
  
- 1           4. (Previously Presented) A pressure sensor as claimed in claim 1 wherein  
2        the filter is a membrane or film.
  
- 1           5. (Original) A pressure sensor as claimed in claim 4 wherein the filter is an  
2        organic film or membrane.
  
- 1           6. (Previously Presented) A pressure sensor as claimed in claim 1 wherein  
2        the sensor is adapted to be fitted to or embedded in a vehicle tyre.
  
- 1           7. (Previously Presented) A pressure sensor as claimed in claim 1 wherein  
2        the integrated circuit is mounted on a lead frame.

1               8. (Original) A pressure sensor as claimed in claim 7 wherein the integrated  
2 circuit and the lead frame are completely encapsulated within the package.

1               9. (Previously Presented) A pressure sensor as claimed in claim 1 wherein  
2 the package is a conventional semiconductor package incorporating an opening.

1               10. (Previously Presented) A pressure sensor as claimed in claim 1 wherein  
2 the package is plastic.

1               11. (Previously Presented) A pressure sensor as claimed in claim 1 wherein  
2 the opening is wholly filled with gel.

1               12. (Previously Presented) A pressure sensor as claimed in claim 1 wherein  
2 the opening is partially filled with a gel.

1               13. (Previously Presented) A pressure sensor as claimed in claim 11 wherein  
2 the gel is a relatively soft gel of relatively low density.

1               14-21. (Canceled)